



INFORMATION DISCLOSURE CITATION
(Use several sheets if necessary)

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Applicant(s)
Consuelo N. Tangpuz et al.

Filing Date	Group Art Unit October 2, 2003
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U.S. PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS

REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS (*Including Author, Title, Date, Pertinent Pages, Etc.*)

TH	5	Joshi, R.; Manatad, R.; Tangpuz, C.; FLIP CHIP IN LEADED MOLDED PACKAGE (FLMP); <i>Fairchild Semiconductor</i> ; pgs 25-29; 2002.

EXAMINER Tu-Re 10

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.